

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74AC32

Quad 2-Input OR Gate

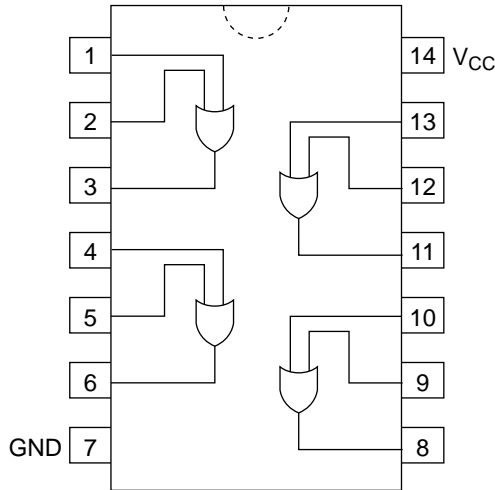
RENESAS

ADE-205-360 (Z)
1st. Edition
Sep. 2000

Feature

- Outputs Source/Sink 24 mA

Pin Arrangement



(Top view)

DC Characteristics (unless otherwise specified)

Item	Symbol	Max	Unit	Condition
Maximum quiescent supply current	I_{CC}	40	μA	$V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5 \text{ V}$, $T_a = \text{Worst case}$
Maximum quiescent supply current	I_{CC}	4.0	μA	$V_{IN} = V_{CC}$ or ground, $V_{CC} = 5.5 \text{ V}$, $T_a = 25^\circ\text{C}$

HD74AC32

AC Characteristics

Item	Symbol	V _{CC} (V) ^{*1}	Ta = +25°C C _L = 50 pF			Ta = -40°C to +85°C C _L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
Propagation delay	t _{PLH}	3.3	1.0	7.0	9.0	1.0	10.0	ns
		5.0	1.0	5.5	7.5	1.0	8.5	
Propagation delay	t _{PHL}	3.3	1.0	7.0	8.5	1.0	9.0	ns
		5.0	1.0	5.0	7.0	1.0	7.5	

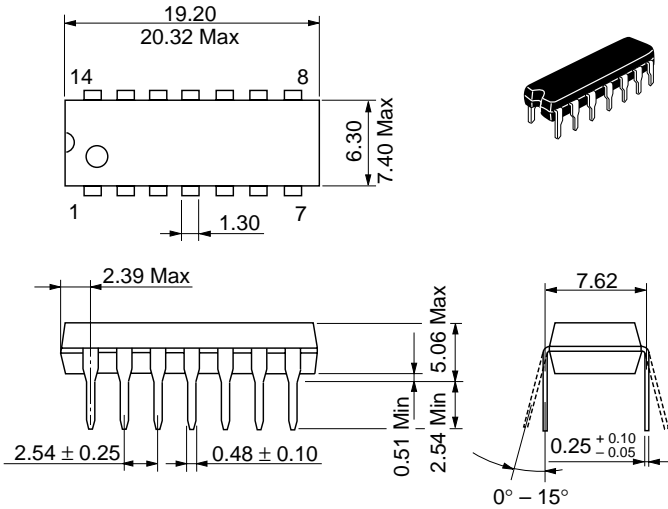
Note: 1. Voltage Range 3.3 is 3.3 V ± 0.3 V
Voltage Range 5.0 is 5.0 V ± 0.5 V

Capacitance

Item	Symbol	Typ	Unit	Condition
Input capacitance	C _{IN}	4.5	pF	V _{CC} = 5.5 V
Power dissipation capacitance	C _{PD}	20.0	pF	V _{CC} = 5.0 V

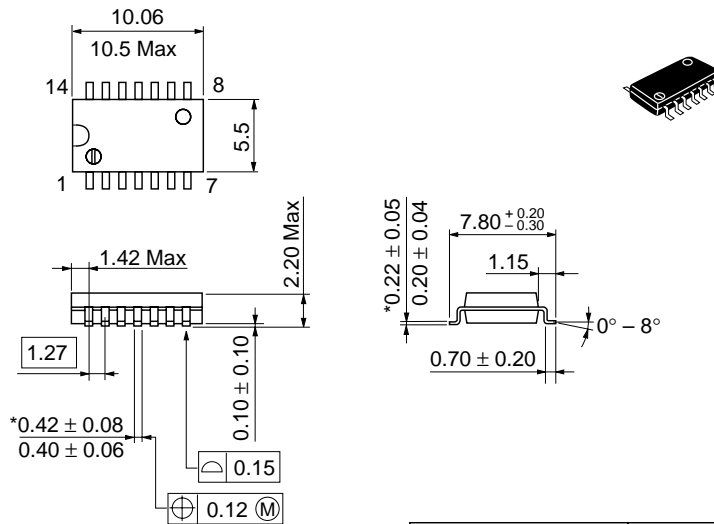
Package Dimensions

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.97 g

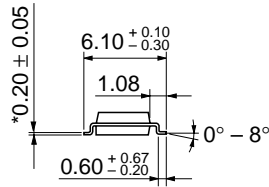
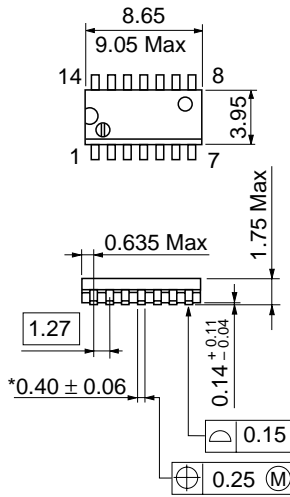
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.23 g

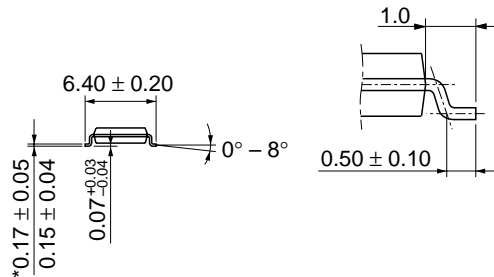
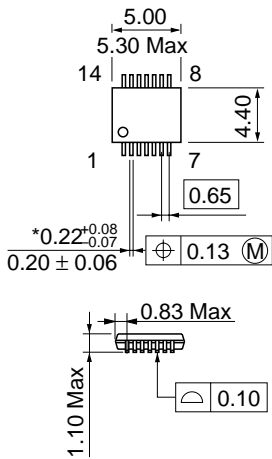
Unit: mm



*Pd plating

Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.13 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-14D
JEDEC	—
EIAJ	—
Mass (reference value)	0.05 g

Cautions

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